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FQA44N30

N-Channel QFET[®] MOSFET

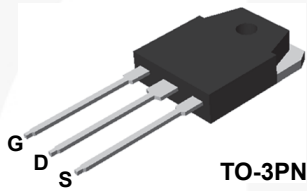
300 V, 43.5 A, 69 mΩ

Description

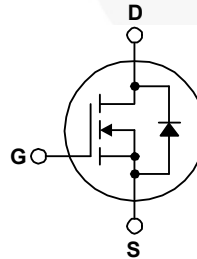
This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.

Features

- 43.5 A, 300 V, $R_{DS(on)} = 69 \text{ m}\Omega$ (Max.) @ $V_{GS} = 10 \text{ V}$, $I_D = 21.75 \text{ A}$
- Low Gate Charge (Typ. 120 nC)
- Low Crss (Typ. 75 pF)
- 100% Avalanche Tested



TO-3PN



Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	FQA44N30	Unit
V_{DSS}	Drain-Source Voltage	300	V
I_D	Drain Current - Continuous ($T_C = 25^\circ\text{C}$)	43.5	A
	- Continuous ($T_C = 100^\circ\text{C}$)	27.5	A
I_{DM}	Drain Current - Pulsed (Note 1)	174	A
V_{GSS}	Gate-Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	1700	mJ
I_{AR}	Avalanche Current (Note 1)	43.5	A
E_{AR}	Repetitive Avalanche Energy (Note 1)	31	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	4.5	V/ns
P_D	Power Dissipation ($T_C = 25^\circ\text{C}$)	310	W
	- Derate above 25°C	2.5	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
T_L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	FQA44N30	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	0.4	$^\circ\text{C}/\text{W}$
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink, Typ.	0.24	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	40	$^\circ\text{C}/\text{W}$

FQA44N30 — N-Channel QFET[®] MOSFET

Package Marking and Ordering Information

Device Marking	Device	Package	Packing Method	Reel Size	Tape Width	Quantity
FQA44N30	FQA44N30	TO-3PN	Tube	N/A	N/A	30 units

Electrical Characteristics $T_c = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
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Off Characteristics

BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{ V}, I_D = 250\ \mu\text{A}$	300	--	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\ \mu\text{A}$, Referenced to 25°C	--	0.32	--	V/ $^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 300\text{ V}, V_{GS} = 0\text{ V}$	--	--	1	μA
		$V_{DS} = 240\text{ V}, T_C = 125^\circ\text{C}$	--	--	10	μA
I_{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30\text{ V}, V_{DS} = 0\text{ V}$	--	--	100	nA
I_{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30\text{ V}, V_{DS} = 0\text{ V}$	--	--	-100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$	3.0	--	5.0	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10\text{ V}, I_D = 21.75\text{ A}$	--	0.055	0.069	Ω
g_{FS}	Forward Transconductance	$V_{DS} = 50\text{ V}, I_D = 21.75\text{ A}$	--	30	--	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 25\text{ V}, V_{GS} = 0\text{ V},$ $f = 1.0\text{ MHz}$	--	4300	5600	pF
C_{oss}	Output Capacitance		--	810	1050	pF
C_{rss}	Reverse Transfer Capacitance		--	75	95	pF

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 150\text{ V}, I_D = 43.5\text{ A},$ $R_G = 25\ \Omega$	--	85	180	ns
t_r	Turn-On Rise Time		--	470	950	ns
$t_{d(off)}$	Turn-Off Delay Time		--	240	490	ns
t_f	Turn-Off Fall Time		(Note 4)	--	230	470
Q_g	Total Gate Charge	$V_{DS} = 240\text{ V}, I_D = 43.5\text{ A},$ $V_{GS} = 10\text{ V}$	--	120	150	nC
Q_{gs}	Gate-Source Charge		--	29	--	nC
Q_{gd}	Gate-Drain Charge		(Note 4)	--	58	--

Drain-Source Diode Characteristics and Maximum Ratings

I_S	Maximum Continuous Drain-Source Diode Forward Current	--	--	43.5	A	
I_{SM}	Maximum Pulsed Drain-Source Diode Forward Current	--	--	174	A	
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_S = 43.5\text{ A}$	--	--	1.5	V
t_{rr}	Reverse Recovery Time	$V_{GS} = 0\text{ V}, I_S = 43.5\text{ A},$	--	320	--	ns
Q_{rr}	Reverse Recovery Charge	$dI_F / dt = 100\text{ A}/\mu\text{s}$	--	3.26	--	μC

Notes:

1. Repetitive Rating : Pulse width limited by maximum junction temperature
2. $L = 1.5\text{ mH}, I_{AS} = 43.5\text{ A}, V_{DD} = 50\text{ V}, R_G = 25\ \Omega,$ Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} \leq 43.5\text{ A}, di/dt \leq 200\text{ A}/\mu\text{s}, V_{DD} \leq BV_{DSS},$ Starting $T_J = 25^\circ\text{C}$
4. Essentially independent of operating temperature

Typical Characteristics

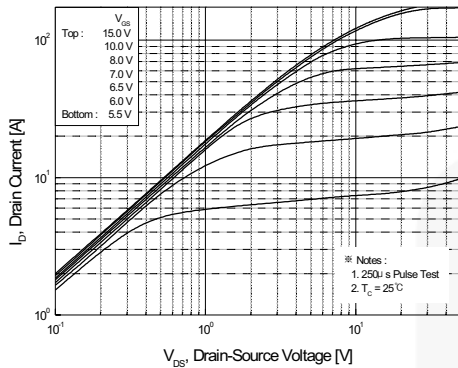


Figure 1. On-Region Characteristics

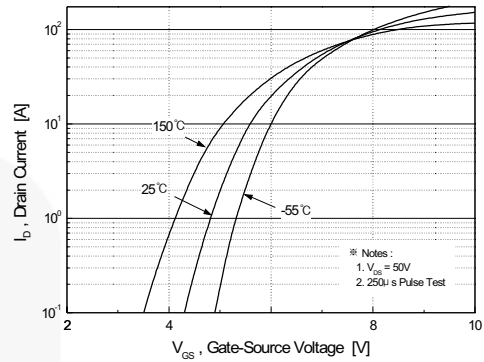


Figure 2. Transfer Characteristics

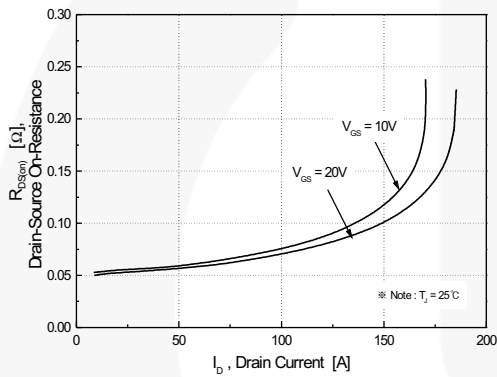


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

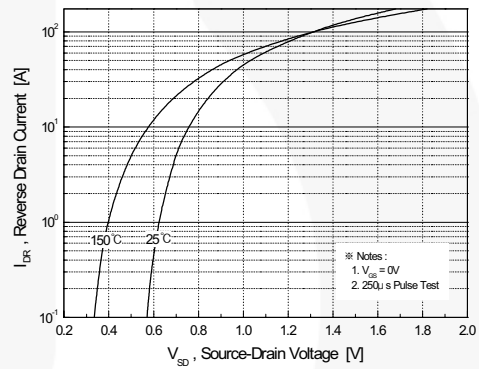


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

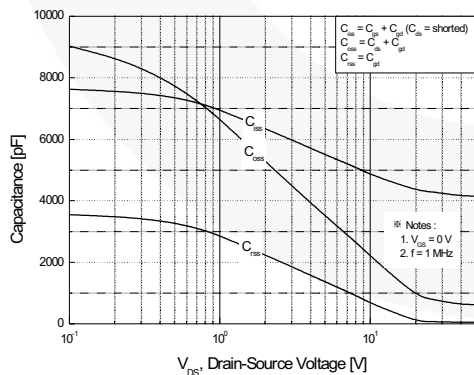


Figure 5. Capacitance Characteristics

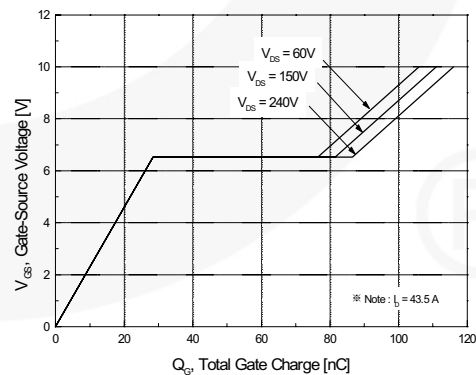


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)

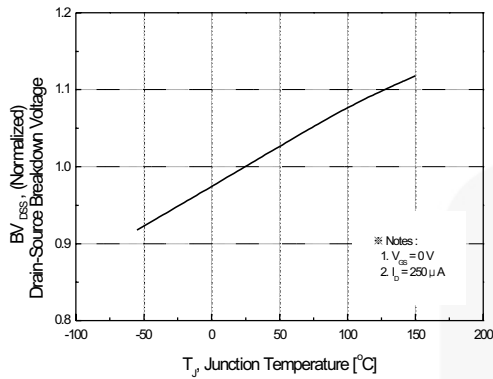


Figure 7. Breakdown Voltage Variation vs. Temperature

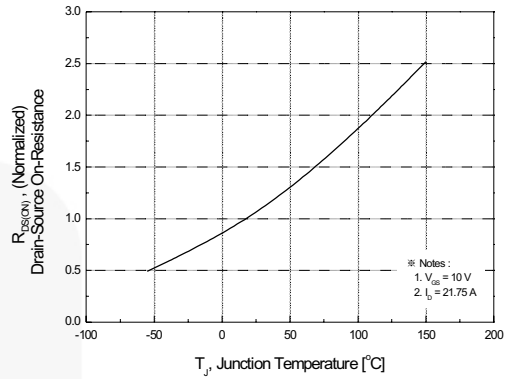


Figure 8. On-Resistance Variation vs. Temperature

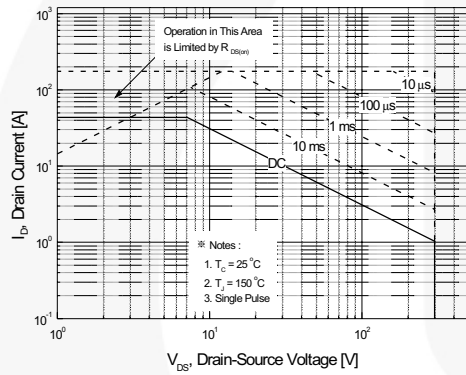


Figure 9. Maximum Safe Operating Area

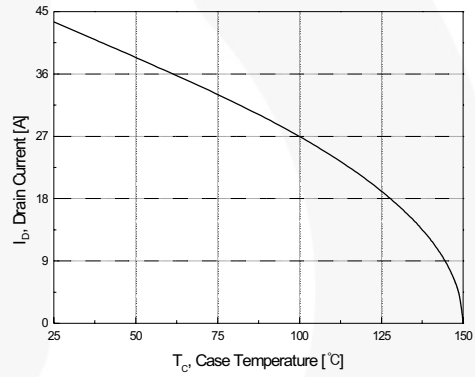


Figure 10. Maximum Drain Current vs. Case Temperature

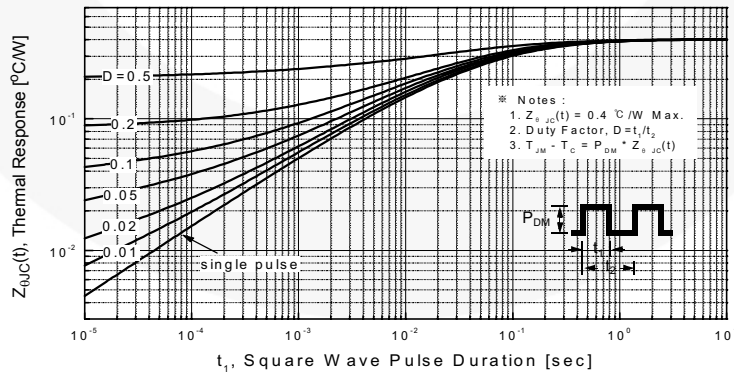


Figure 11. Transient Thermal Response Curve

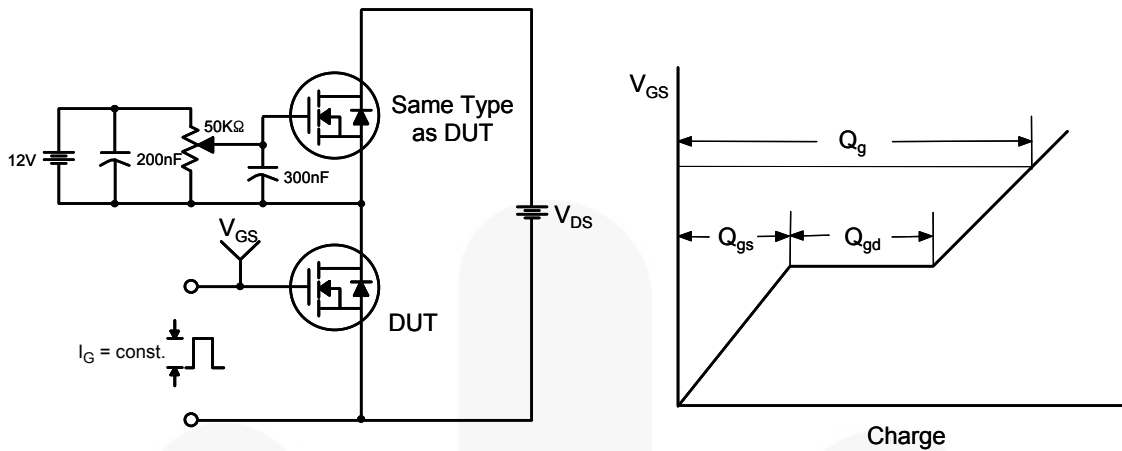


Figure 12. Gate Charge Test Circuit & Waveform

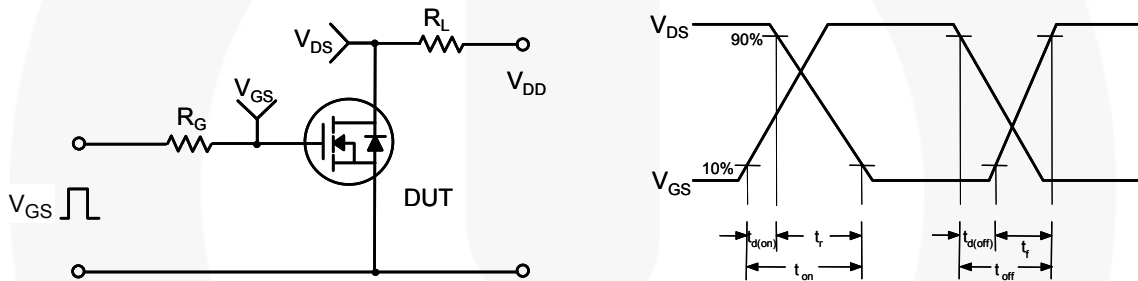


Figure 13. Resistive Switching Test Circuit & Waveforms

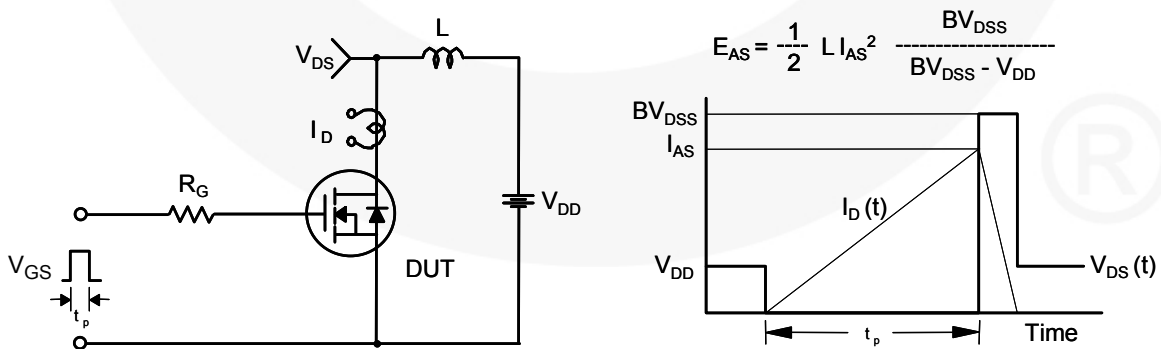


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

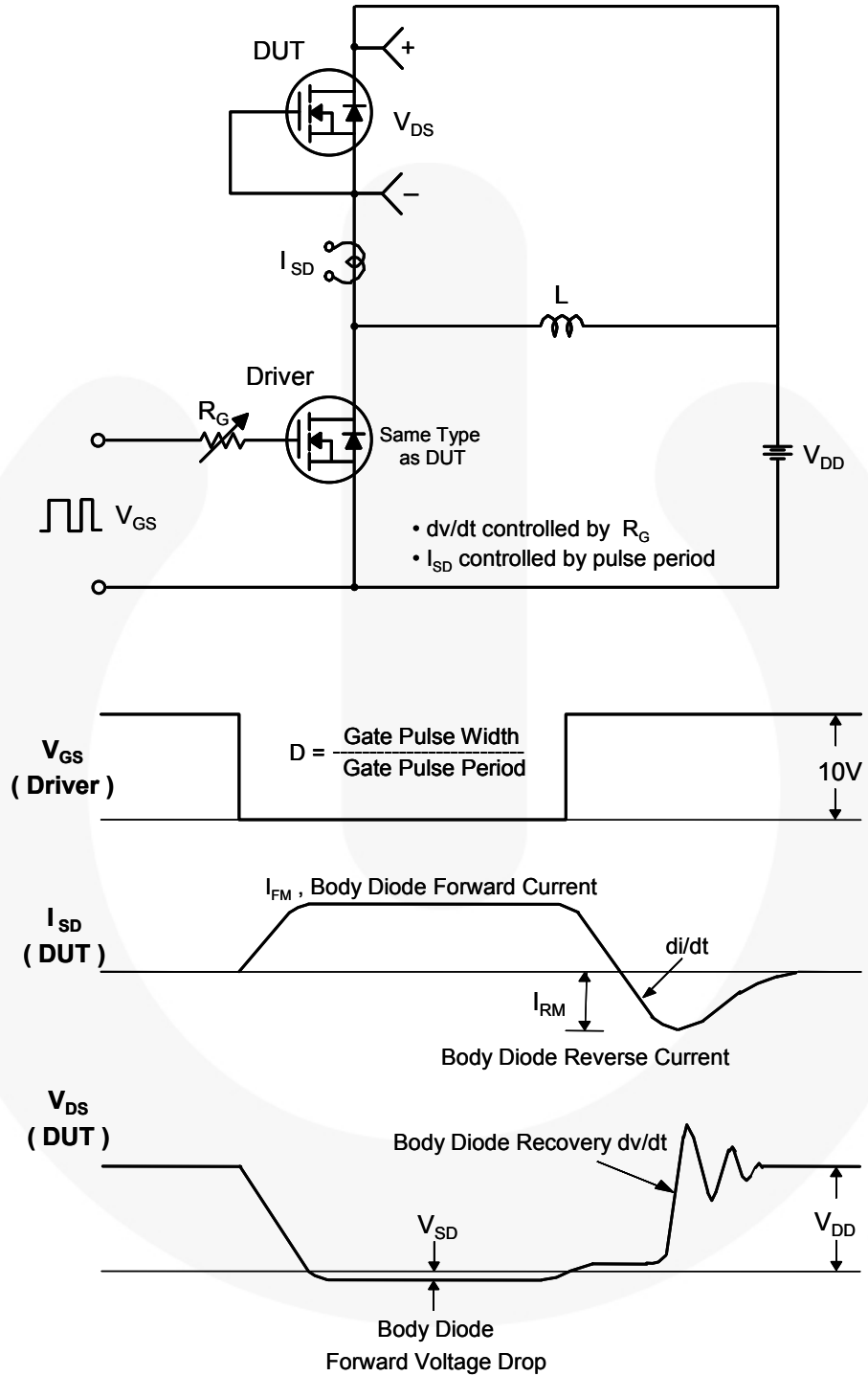
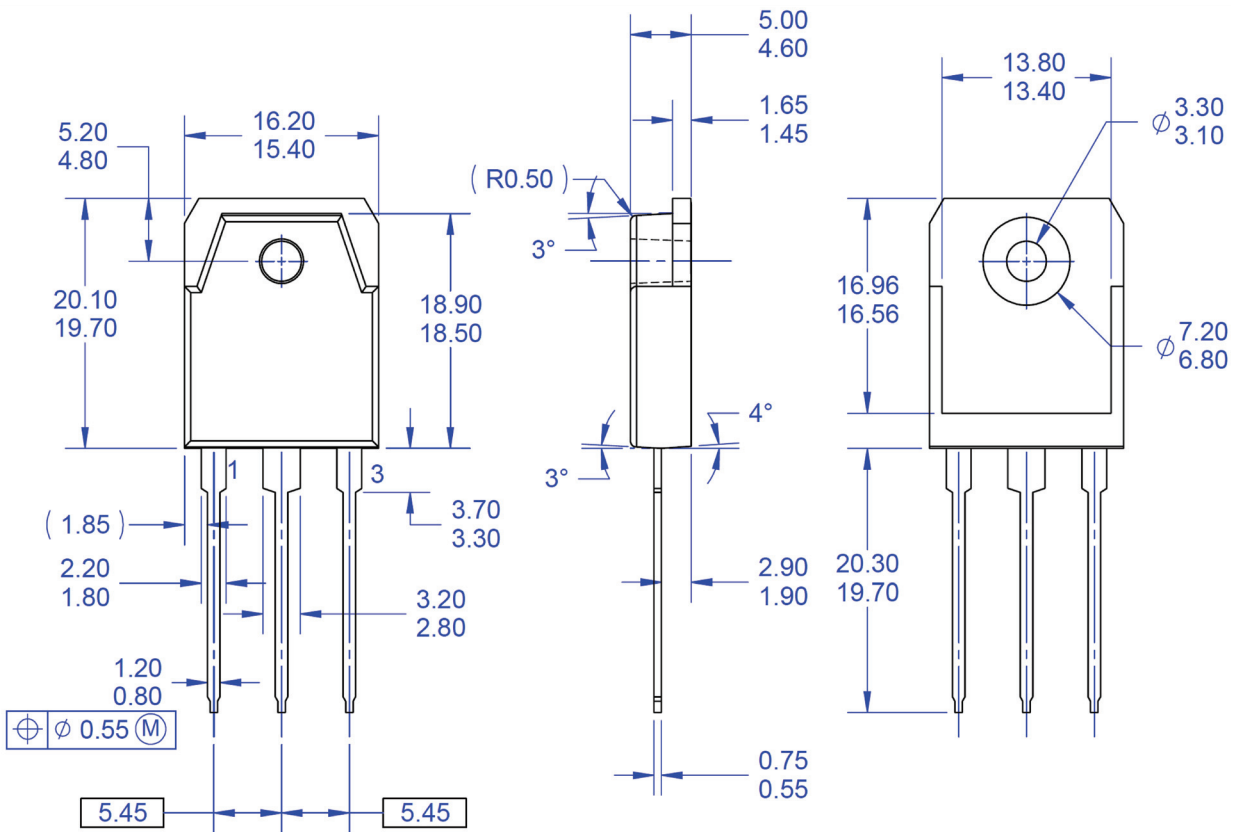


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions



NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO EIAJ SC-65 PACKAGING STANDARD.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSION AND TOLERANCING PER ASME14.5-2009.
- D) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- E) DRAWING FILE NAME: TO3PN03AREV1.
- F) FAIRCHILD SEMICONDUCTOR.

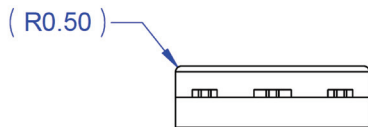


Figure 16. TO3PN, 3-Lead, Plastic, EIAJ SC-65

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